

AMENDMENTS TO THE CLAIMS

1. (Currently amended) A cooling system for a personal computer, the cooling system comprising:
 - a computer chassis;
 - a motherboard mounted inside the computer chassis, the motherboard for coupling a number of electronic components that generate heat during operation, and
 - a fan mechanically coupled to the computer chassis and configured to direct an airflow through the fan from outside the computer chassis to inside the computer chassis, the air flow cooling the electronic components;

wherein the computer chassis includes a plurality of air outlets located far from electronic components on the motherboard that generate a relatively large amount of heat, thereby avoiding a hotter air flow near those components, and located near electrical components on the motherboard for which less heat dissipation is desired, thereby causing a hotter air flow near those components.
2. (Original) The cooling system of claim 1, wherein the fan is mounted on a wall of the computer chassis.
3. (Original) The cooling system of claim 1, further comprising:
 - a motherboard with a socket for receiving a CPU;

wherein the fan is configured to blow air directly towards the socket from outside the computer chassis.
4. (Original) The system of claim 1, further comprising:
 - a filter mounted in a path of an airflow from the fan, the filter for removing particles from air outside the computer chassis before being blown inside the computer chassis.

5-6. (Canceled)

7. (New) An apparatus for cooling components on a motherboard of a personal computer, the apparatus comprising:
 - a motherboard containing a plurality of electronic components that generate heat during operation, a high-heat subset of the electrical components generating a relatively high amount of heat and a low-heat subset of the electrical components generating a relatively low amount of heat, and
 - a chassis covering the motherboard and including a plurality of air outlets, wherein the air outlets are located closer to the low-heat electrical components than to the high-heat electronic components, thereby generally directing heated exhaust air out of the chassis near the low-heat electrical components instead of near the high-heat electrical components;
 - a fan mechanically coupled to the chassis and configured to direct an airflow into the chassis to cool the electronic components on the motherboard.

8. (New) The apparatus of claim 7, wherein the fan is mounted on a wall of the chassis.

9. (New) The apparatus of claim 7, further comprising:
 - a CPU mounted on the motherboard, wherein the fan is configured to blow air directly towards the CPU.
10. (New) The apparatus of claim 7, further comprising:
 - a filter mounted in a path of the airflow from the fan, the filter removing particles from air outside the chassis before being blown inside the chassis.